# **SC-74 Quad Transient Voltage Suppressor**

## for ESD Protection

This quad monolithic silicon voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems and other applications. This quad device provides superior surge protection over current quad Zener MMQA series by providing up to 350 watts peak power.

#### **Features**

- SC-74 Package Allows Four Separate Unidirectional Configurations
- Peak Power 350 W, 8 x 20 μS
- ESD Rating of Class N (Exceeding 25 kV) per the Human Body Model
- ESD Rating:

IEC 61000-4-2 (ESD) 15 kV (air) 8 kV (contact)

IEC 61000-4-4 (EFT) 40 A (5/50 ns)

IEC 61000–4–5 (lightning) 23 A (8/20 μs)

- UL Flammability Rating of 94 V-0
- Pb-Free Packages are Available

#### **Typical Applications**

 Hand Held Portable Applications such as Cell Phones, Pagers, Notebooks and Notebook Computers

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Power Dissipation 8 x 20 μS @ T <sub>A</sub> = 25°C (Note 1)	P <sub>pk</sub>	350	W
Total Power Dissipation on FR–5 Board @ T <sub>A</sub> = 25°C (Note 2) Derate Above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Lead Solder Temperature Maximum 10 Seconds Duration	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Non-repetitive current pulse 8 x 20 μS exponential decay waveform
- 2.  $FR-5 = 1.0 \times 0.75 \times 0.62$  in.



## ON Semiconductor®

http://onsemi.com

## SC-74 QUAD TRANSIENT VOLTAGE SUPPRESSOR 350 WATTS PEAK POWER 5 VOLTS



SC-74 CASE 318F STYLE 1

#### MARKING DIAGRAM



xxx = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### **PIN ASSIGNMENT**



PIN 1. CATHODE

2. ANODE

3. CATHODE

4. CATHODE

5. ANODE 6. CATHODE

#### **DEVICE MARKING INFORMATION**

See specific marking information in the device marking column of the Electrical Characteristics table on page 2 of this data sheet.

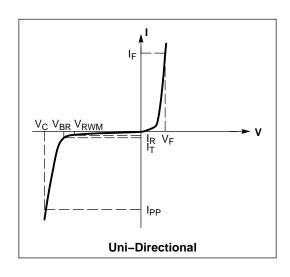
#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter		
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current		
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>		
V <sub>RWM</sub> Working Peak Reverse Voltage			
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>		
$V_{BR}$	Breakdown Voltage @ I <sub>T</sub>		
I <sub>T</sub>	Test Current		
$\Theta V_{BR}$	Maximum Temperature Coefficient of V <sub>BR</sub>		
lF	Forward Current		
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>		
Z <sub>ZT</sub>	Maximum Zener Impedance @ I <sub>ZT</sub>		
I <sub>ZK</sub>	Reverse Current		
$Z_{ZK}$	Maximum Zener Impedance @ I <sub>ZK</sub>		



## **ELECTRICAL CHARACTERISTICS - UNIDIRECTIONAL**

			Breakdown Leakage Voltage Current			rse age	Max Reverse Voltage (Clamping Voltage) At Specified Reverse Surge Current (I <sub>RSM</sub> )		Max Reverse Voltage (Clamping Voltage) At Specified Reverse Surge Current (I <sub>RSM</sub> )		Capacitance @ 0 Volt Bias, 1 MHz		
	Device	V <sub>BR</sub> (V)		I <sub>T</sub> I <sub>R</sub> V <sub>R</sub>		V <sub>R</sub>	I <sub>RSM</sub> (8x20 μs)	V <sub>RSM</sub> (8x20 μs)	I <sub>RSM</sub> (8x20 μs)	V <sub>RSM</sub> (8x20 μs)	(pF)		
Device	Marking	Min	Nom	Max	(mA)	(μ <b>A</b> )	(V)	(A)	(V)	(A)	(V)	Min	Max
SMS05T1	5V0	6.0	_	7.2	1.0	20	5.0	5.0	9.8	23	15.5	250	400
SMS12T1	12V	13.3	_	15	1.0	1.0	12	5.0	19.0	15	23.0	80	150
SMS15T1	15V	16.7	-	18.5	1.0	1.0	15	5.0	24.0	12	29.0	60	125
SMS24T1	24V	26.7	_	32	1.0	1.0	24	5.0	40.0	8	44.0	40	75

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>		
SMS05T1	SC-74			
SMS05T1G	SC-74 (Pb-Free)	3000 / Tape & Reel		
SMS12T1	SC-74			
SMS12T1G	SC-74 (Pb-Free)	3000 / Tape & Reel		
SMS15T1	SC-74			
SMS15T1G	SC-74 (Pb-Free)	3000 / Tape & Reel		
SMS24T1	SC-74	3000 / Tape & Reel		
SMS24T1G	SC-74 (Pb-Free)			

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

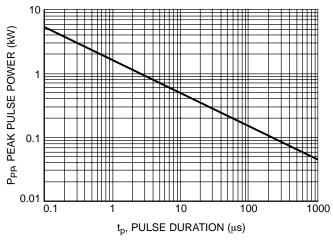


Figure 1. Non-Repetitive Peak Pulse Power versus Pulse Time

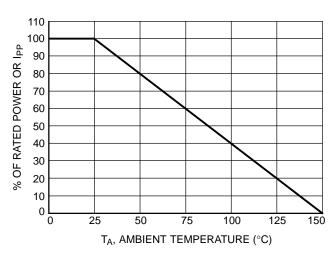


Figure 2. Power Derating Curve

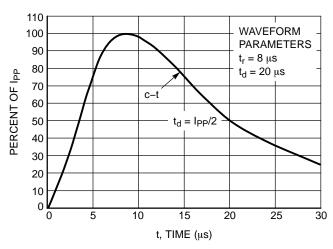


Figure 3. Pulse Waveform

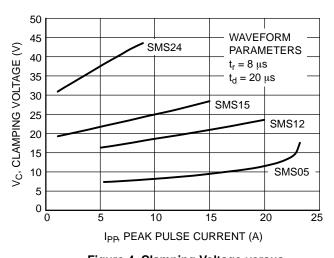


Figure 4. Clamping Voltage versus
Peak Pulse Current

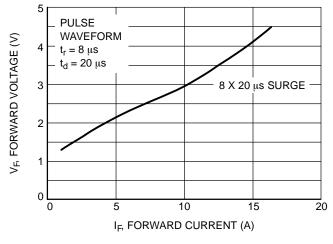


Figure 5. 8 x 20 µs V<sub>F</sub>

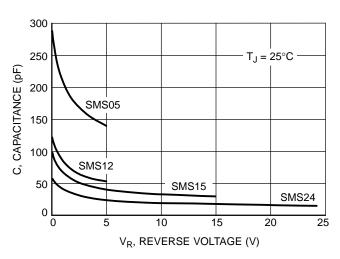
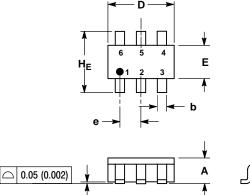
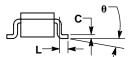


Figure 6. Typical Capacitance (SMS05 Series)

#### PACKAGE DIMENSIONS

SC-74 (SC-59ML) CASE 318F-05 ISSUE M





#### NOTES

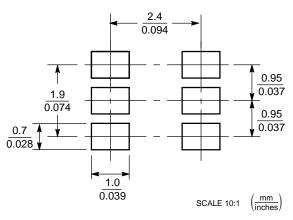
- DIMENSIONING AND TOLERANCING PER
   ANSI V14 FM 1082
- ANSI Y14.5M, 1982.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- OF BASE MATERIAL. 4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

	М	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.37	0.50	0.010	0.015	0.020	
С	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
E	1.30	1.50	1.70	0.051	0.059	0.067	
е	0.85	0.95	1.05	0.034	0.037	0.041	
L	0.20	0.40	0.60	0.008	0.016	0.024	
HE	2.50	2.75	3.00	0.099	0.108	0.118	
A	0°	_	10°	0°	_	10°	

#### STYLE 1: PIN 1.

- IN 1. CATHODE 2. ANODE
- 3. CATHODE
- 4. CATHODE
- 5. ANODE
- 6 CATHODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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